

Application Serial No: 10/576,054
Responsive to the Office Action mailed on: May 28, 2008

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IN THE CLAIMS

Amendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-7. (Cancelled)

8.. (New) A circuit board comprising:

an elongate wiring board having a first end and a second end;

a first bendable terminal plate attached to the first end of the wiring board; and

a second bendable terminal plate attached to the second end of the wiring board;

wherein the wiring board includes an intermediate stress concentrating portion located between the first and second ends, a first mounting portion located between the first end and the intermediate stress concentrating portion, and a second mounting portion located between the second end and the intermediate stress concentrating portion, the intermediate stress concentrating portion having a smaller cross section than the first and second mounting portions;

wherein the circuit board further comprises a first electronic component mounted on the first mounting portion of the wiring board between the first terminal plate and the intermediate stress concentrating portion, and a second electronic component mounted on the second mounting portion of the wiring board between the second terminal plate and the intermediate stress concentrating portion.

9. (New) The circuit board according to claim 8, further comprising a second stress concentrating portion located between the first end of the wiring board and the intermediate stress concentrating portion, and a third stress concentrating portion located between the second end of the wiring board and the intermediate stress concentrating portion;

wherein the first electronic component is mounted on the first mounting portion of

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the wiring board between the second stress concentrating portion and the intermediate stress concentrating portion, and the second electronic component is mounted on the second mounting portion of the wiring board between the third stress concentrating portion and the intermediate stress concentrating portion.

10. (New) The circuit board according to claim 8, wherein the intermediate stress concentrating portion comprises a recess for partially reducing a width of the wiring board.

11. (New) The circuit board according to claim 8, wherein the intermediate stress concentrating portion comprises a hole penetrating the wiring board.

12. (New) The circuit board according to claim 8, wherein the intermediate stress concentrating portion comprises a groove for partially reducing a thickness of the wiring board.

13. (New) The circuit board according to claim 12, wherein the groove is formed in a surface of the wiring board that is opposite to another surface upon which the first and second electronic components are mounted.

14. (New) The circuit board according to claim 9, wherein at least one of the intermediate stress concentration portion, the second stress concentration portion, and the third stress concentration portion comprises a recess for partially reducing a width of the wiring board.

15. (New) The circuit board according to claim 9, wherein at least one of the intermediate stress concentration portion, the second stress concentration portion, and the third stress concentration portion comprises a hole penetrating the wiring boards.

16. (New) The circuit board according to claim 9, wherein at least one of the intermediate stress concentration portion, the second stress concentration portion, and the third stress concentration portion comprises a groove for partially reducing a thickness of

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the wiring board.

17. (New) The circuit board according to claim 9, wherein at least one of the intermediate stress concentration portion, the second stress concentration portion, and the third stress concentration portion comprises a combination of a recess and a groove, the recess partially reducing a width of the wiring board, the groove partially reducing a thickness of the wiring board.